



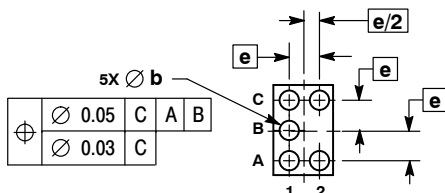
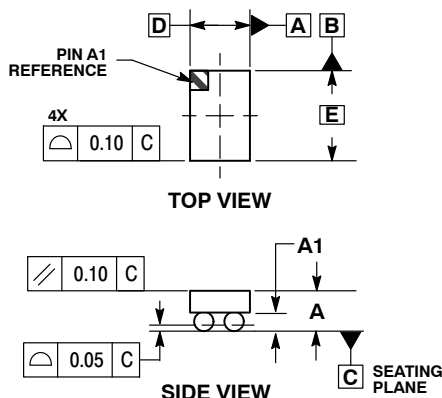
SCALE 4:1

### 5 PIN FLIP-CHIP, 0.9x1.4

#### CASE 499BG

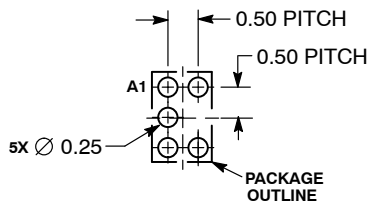
#### ISSUE O

DATE 21 JUL 2009



**BOTTOM VIEW**

### SOLDERING FOOTPRINT\*

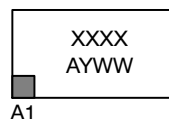


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.44	0.50
A1	0.15	0.19
b	0.21	0.25
D	0.90 BSC	
E	1.40 BSC	
e	0.50 BSC	

### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>5 PIN FLIP-CHIP, 1.4X0.9, 0.5 PITCH</b>	<b>PAGE 1 OF 1</b>

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